



materials



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ICKEM2018 - Hierarchically Structured Materials (HSM)

Guest Editor:

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Deadline for manuscript
submissions:

closed (31 October 2018)

Message from the Guest Editor

Dear Colleagues,

The 8th International Conference on Key Engineering Materials (ICKEM 2018) (<http://www.ickem.org/>) will be held, 16 – 18 March, 2018, at the Osaka International Convention Center, Osaka, Japan.

The purpose of the 8th International Conference on Key Engineering Materials is to bring together researchers, engineers and practitioners interested in the whole range of fields related to the materials. Papers presenting original works are invited on the topics listed below.

- Biomaterials in Different Applications
- Novel Composite Materials in Vivid Applications
- Application of Novel Materials in Civil Engineering
- Advances in Materials and Manufacturing Technology
- Materials and Technologies in Environmental Engineering
- Studies on Corrosion, Coating, and Aspects of Chemical Engineering
- Electrical, Electronic, and Optoelectronic Materials: Synthesis and Applications
- Trends in the Development of Nanomaterials, Nanocomposites and Nanotechnology

We invite researchers to submit their contributions to this Special Issue.

Prof. Alexander K



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Special Issue



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Editor-in-Chief

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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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